Claims:

1. An apparatus for processing a substrate, comprising:

a process chamber having a substrate support disposed therein to support a processing surface of a substrate at a desired position within the process chamber;

a first injector to provide a first process gas over the processing surface of the substrate in a first direction;

a second injector to provide a second process gas over the processing surface of the substrate in a second direction different from the first direction, wherein the second injector includes one or more nozzles that adjust at least one of a gas flow speed, a gas flow shape, and a gas flow direction of the second process gas;

an exhaust port disposed opposite the first injector to exhaust the first and second process gases from the process chamber; and

wherein the one or more nozzles are adjustable nozzles and wherein the apparatus further includes one or more controllable knobs that adjust at least one of an angle of the one or more adjustable nozzles with respect to the substrate or a cross-sectional shape of the one or more adjustable nozzles.

2. The apparatus of claim 1, wherein the second injector includes a plurality of adjustable nozzles, wherein each of a first adjustable nozzle and a second adjustable nozzle in the plurality of adjustable nozzles are separately controllable by the one or more controllable knobs, and wherein the first adjustable nozzle provides the second process gas at a different angle than the second adjustable nozzle.